

ATTY DKT. NO.: U.S. SERIAL NO.:

CONF. No.: 4228

HSU, ET AL.

AMAT/5614.D1/CMP/CMP/RKK

10/792,069 CONF. NO
MARCH 3, 2004
APPLIED MATERIALS, INC.
INTEGRATED MULTI-STEP GAP FILL AND FEATURE
PLANARIZATION FOR CONDUCTIVE MATERIALS

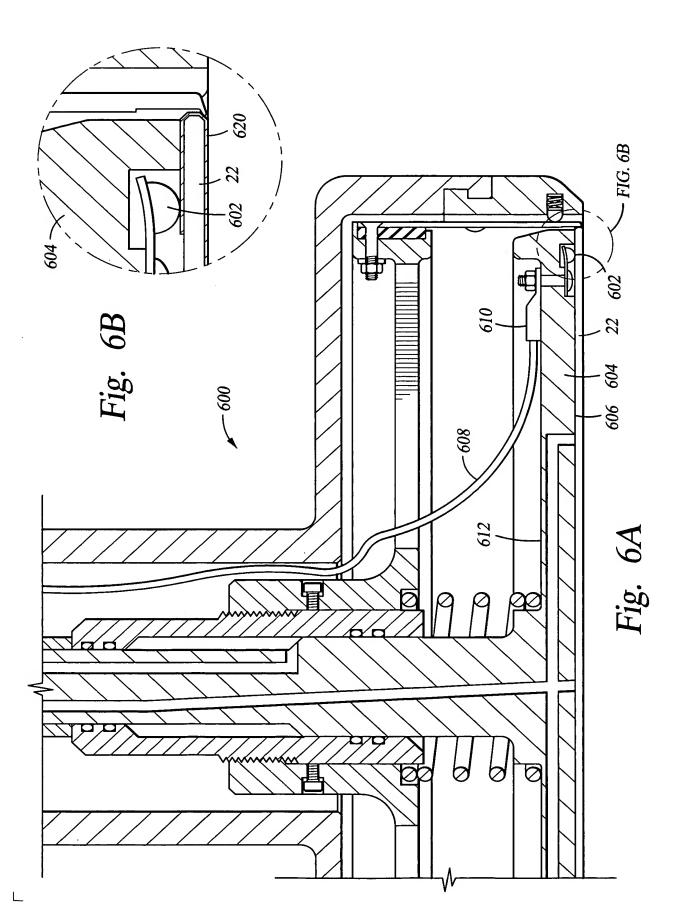
INVENTOR: REPLACEMENT DRAWINGS

FILED: APPLICANT: TITLE:

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